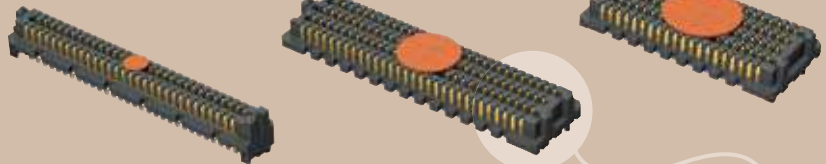




SEAM-20-02.0-S-10-2-A-K-TR



SEAM-30-03.5-S-04-2-A-K-TR

SEAM-30-02.0-S-08-2-A-K-TR

(1,27mm) .050"

SEAM SERIES

# HIGH SPEED/HIGH DENSITY OPEN PIN FIELD

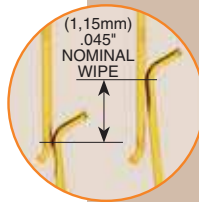
## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?SEAM](http://www.samtec.com?SEAM)

- Insulator Material:** Black LCP
- Contact Material:** Copper Alloy
- Solder Charge:** 95.5% Sn, 3.8% Ag, 0.7% Cu (Tin/Lead also available. Call Samtec.)
- Operating Temp Range:** -55°C to +125°C
- Plating:** Au or Sn over 50µ" (1,27µm) Ni
- Contact Resistance:** 5.5 mΩ
- Working Voltage:** 240 VAC
- RoHS Compliant:** Yes
- Lead-Free Solderable:** Yes



Mates with: SEAF, SADL



Up to 500 Pins

5, 8 and 10 row footprint compatible with SamArray®. Samples recommended.

Solder charges



Low Insertion/Extraction Forces

7mm Stack Height	Rated @ 3dB Insertion Loss
Single-Ended Signaling	9.5 GHz / 19 Gbps
Differential Pair Signaling	10.5 GHz / 21 Gbps

Performance data for other stack heights and complete test data available at [www.samtec.com?SEAM](http://www.samtec.com?SEAM) or contact [sig@samtec.com](mailto:sig@samtec.com)

CURRENT RATING	
AMBIENT TEMP	SEAM/SEAF
20°C	2.3A
40°C	2A
60°C	1.75A
95°C	1.14A

30 ADJACENT POSITIONS POWERED

**Industry Standards**

PISMO 2  
VITA 47  
VITA 57

**Protocols Supported**

Fibre Channel  
Rapid I/O  
PCI Express®  
SATA  
Infiniband

Download app notes at [www.samtec.com/appnote](http://www.samtec.com/appnote)  
Contact SIG @ samtec.com for questions on protocols

## SEAM - NO. PINS PER ROW - LEAD STYLE - PLATING OPTION - NO. OF ROWS - SOLDER TYPE - A - K - TR

-10, -15, -20, -30, -40, -50  
(-10 only available in 04 row)  
(-15 only available in 10 row)

Specify LEAD STYLE from chart

NO. OF ROWS	B
-04	(7,06) .278
-05, -06	(9,60) .378
-08	(12,14) .478
-10	(14,68) .578

-L = 10µ" (0,25µm) Gold on contact area, Matte Tin on solder tail

-S = 30µ" (0,76µm) Gold on contact area, Matte Tin on solder tail

-04 = Four Rows (-06.5 not available)

-05 = Five Rows (-06.5 not available)

-06 = Six Rows (-06.5 not available)

-08 = Eight Rows

-10 = Ten Rows

-2 = Lead-Free Solder Charge

-A = Alignment Pins (Required. Arrays will not self-center on solder pads)

-K = Polyimide film Pick & Place Pad

-TR = Tape & Reel

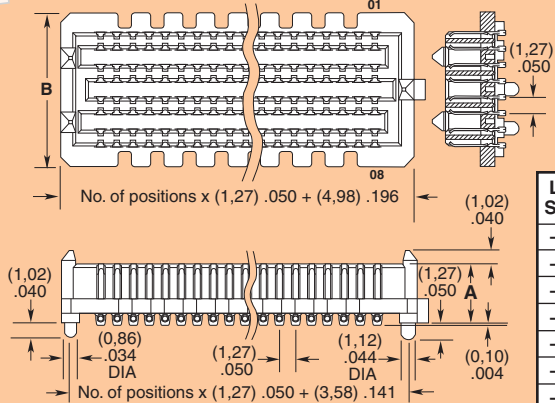
### ALSO AVAILABLE

Rugged solder crimp option. Call Samtec.

## DIFFERENTIAL

ARRAY	PAIR COUNT
40x8	80
40x6	60
30x10	75
30x8	60
30x6	45
50x10	125
50x8	100
40x10	100
20x10	50
20x8	40
20x5	25

Note: Some sizes, styles and options are non-standard, non-returnable.



LEAD STYLE	A
-02.0	(4,60) .181
-03.0	(5,59) .220
-03.5	(6,10) .240
-06.5	(6,40) .252
-07.0	(9,60) .378
-09.0	(11,60) .457
-11.0	(13,60) .535

SEAM LEAD STYLE	MATED HEIGHTS				
	SEAF LEAD STYLE				
	-05.0	-06.0	-06.5	-07.5	-08.0
-02.0	7mm	8mm	8.5mm	9.5mm	10mm
-03.0	8mm	9mm	9.5mm	10.5mm	11mm
-03.5	8.5mm	9.5mm	10mm	11mm	11.5mm
-06.5	11.5mm	12.5mm	13mm	14mm	14.5mm
-07.0	12mm	13mm	13.5mm	14.5mm	15mm
-09.0	14mm	15mm	15.5mm	16.5mm	17mm
-11.0	16mm	17mm	17.5mm	18.5mm	19mm

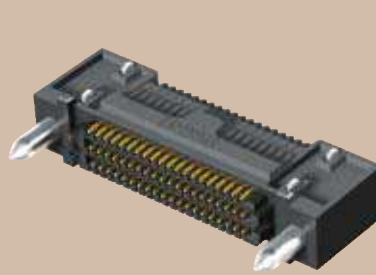
Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

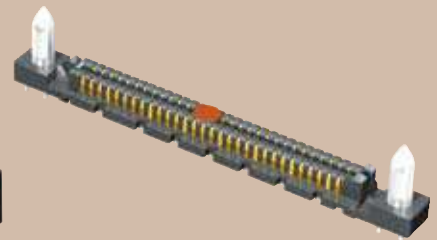


(1,27mm) .050"

SEAM-RA, SEAM-GP SERIES



SEAM-20-01-L-06-2-RA-GP-TR



SEAM-30-02.0-L-04-2-A-GP-K-TR

# HI-DENSITY RIGHT ANGLE OPEN PIN FIELD

Mates with:  
SEAF-RA, SADL, SEAF

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?SEAM](http://www.samtec.com?SEAM)

- Insulator Material:** Black LCP
- Contact Material:** Copper Alloy
- Current Rating:** Testing Now!
- Operating Temp Range:** -55°C to +125°C
- Plating:** Au or Sn over 50µ" (1,27µm) Ni
- Contact Resistance:** 19 mΩ max
- Working Voltage:** 260 VAC
- RoHS Compliant:** Yes
- Lead-Free Solderable:** Yes



-20, -30,  
-40, -50

-L  
= 10µ" (0,25µm)  
Gold on contact area,  
Matte Tin on solder tail

-04 = Four Rows  
-06 = Six Rows  
-08 = Eight Rows  
-10 = Ten Rows

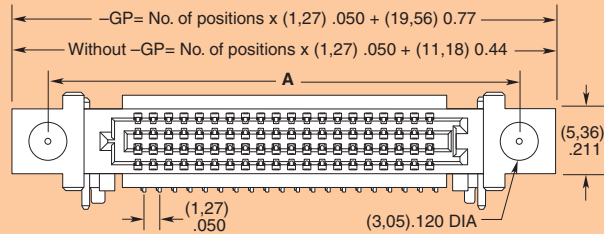
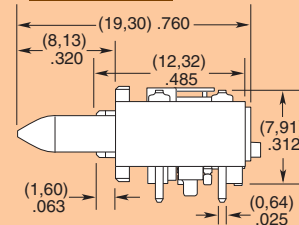
-2 = Lead-Free Tin Alloy  
95.5% Sn/  
3.8% Ag/  
0.7% Cu Solder Charge

-GP = Guide Post

-TR = Tape & Reel

NUMBER PINS PER ROW	A
-20	(38,94) 1.533
-30	(51,64) 2.033
-40	(64,34) 2.533
-50	(77,04) 3.033

Note: Other Gold plating options available. Contact Samtec.



## ALSO AVAILABLE

Tin-Lead Solder Charge.  
Polyimide film Pick & Place Pad.  
Call Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.



Mates with:  
SEAF-RA-GP

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?SEAM-GP](http://www.samtec.com?SEAM-GP)

- Insulator Material:** Black LCP
- Contact Material:** Copper Alloy
- Current Rating:** 2.7 A
- Operating Temp Range:** -55°C to +125°C
- Plating:** Au over 50µ" (1,27µm) Ni
- Contact Resistance:** 5.5 mΩ
- Working Voltage:** 240 VAC
- Mated Cycles:** 100
- RoHS Compliant:** Yes
- Lead-Free Solderable:** Yes



-20, -30,  
-40, -50

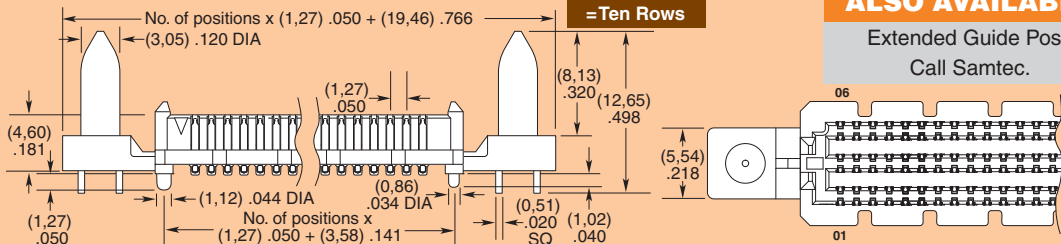
-L  
= 10µ" (0,25µm)  
Gold on contact area,  
Matte Tin on solder tail

-04 = Four Rows  
-06 = Six Rows  
-08 = Eight Rows  
-10 = Ten Rows

-2 = Lead-Free Tin Alloy  
95.5% Sn/3.8%  
Ag/0.7% Cu Solder Charge

-K = Polyimide film Pick & Place Pad

-TR = Tape & Reel (Not available with 50 positions)



## ALSO AVAILABLE

Extended Guide Post.  
Call Samtec.

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)